

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.: 303.672US1

Serial No.: 09/483,881

Filed: January 18, 2000

Due Date: February 26, 2003

Examiner: Ha Nguyen

Group Art Unit: 2812

Box AF

Commissioner for Patents

Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

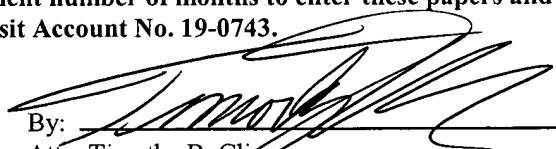
☒ A return postcard.

☒ A Response Under 1.116 (6 Pages).

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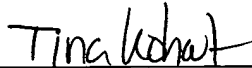
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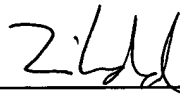
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Box AF, Commissioner for Patents, Washington, D.C. 20231, on this 25 day of January, 2003.

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